


Client Code: QCO.256D1/0808313D1

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To the Director, U.S. Patent and Trademark Office: Please record the attached original documents or copy thereof.

<b>1. Name of conveying parties:</b> 1) James Randolph Webster 2) Thanh Nghia Tu 3) Xiaoming Yan 4) Wonsuk Chung  Additional name(s) of conveying party(ies) attached? ( ) Yes (X) No	<b>2. Name and address of receiving party:</b> <b>Name:</b> QUALCOMM MEMS Technologies, Inc. <b>Street Address:</b> 5775 Morehouse Drive <b>City:</b> San Diego <b>State:</b> CA <b>ZIP:</b> 92121  Additional name(s) of receiving party(ies) attached? ( ) Yes (X) No
<b>3. Nature of conveyance:</b> (✓) Assignment ( ) Security Agreement ( ) Merger ( ) Change of Name ( ) Other:  <b>Execution Date:</b>  1) June 13, 2008 2) June 20, 2008 3) June 13, 2008 4) June 13, 2008	<b>4. US or PCT Application number(s) or US Patent number(s):</b>  (X) Patent Application No.: 12/939,909 <b>Filing Date:</b> November 4, 2010  Additional numbers attached? ( ) Yes (X) No
<b>5. Party to whom correspondence concerning document should be mailed:</b>  <b>Customer No.</b> 59,747 <b>Address:</b> Knobbe, Martens, Olson & Bear, LLP 2040 Main Street, 14 <sup>th</sup> Floor Irvine, CA 92614 <b>Return Fax:</b> (949) 760-9502 <b>Attorney's Docket No.:</b> QCO.256D1/080313D1	<b>6. Total number of applications and patents involved:</b> 1
<b>7. Total fee (37 CFR 1.21(h)):</b> \$40 (X) Authorized to be charged to deposit account	<b>8. Deposit account number:</b> 11-1410  Please charge this account for any additional fees which may be required, or credit any overpayment to this account.
<b>9. Statement and signature.</b>  To the best of my knowledge and belief, the foregoing information is true and correct, and any attached copy is a true copy of the original document.  <div style="display: flex; justify-content: space-between;"> <div> <u>Jeremy R. Pierce</u>            Name of Person Signing             59,034            Registration No.         </div> <div style="text-align: center;">             Signature         </div> <div>           November 4, 2010            Date         </div> </div> <div style="text-align: center; margin-top: 20px;">           Total number of pages including cover sheet, attachments and document: 6         </div>	

Documents transmitted via Facsimile to be recorded with required cover sheet information to:

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**PATENT**  
**REEL: 025300 FRAME: 0310**

CH \$40.00 111410 12939909

Application No.: 12/133,813  
Filing Date: June 5, 2008

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### ASSIGNMENT

WHEREAS, we, James Randolph Webster, a U.S. citizen, residing at 42 Avenida Espana, San Jose, CA 95139, Thanh Nghia Tu, a U.S. citizen, residing at 526 Doyle Road #4, San Jose, CA 95129, Xiaoming Yan, a Chinese citizen, residing at 865 Blair Ave. #1, Sunnyvale, CA 94087, and Wonsuk Chung, a citizen of the Republic of Korea, residing at 4877 Lago Vista Circle, San Jose, CA 95129 have invented certain new and useful improvements in a LOW TEMPERATURE AMORPHOUS SILICON SACRIFICIAL LAYER FOR CONTROLLED ADHESION IN MEMS DEVICES for which we caused to be filed an application for Letters Patent in the United States; and we hereby authorize and request the attorneys of Knobbe, Martens, Olson & Bear, LLP, Customer No. 59,747, to insert here in parentheses (Application Number 12/133.813, filed June 5, 2008) the filing date and application number of said application when known;

AND WHEREAS, QUALCOMM MEMS Technologies, Inc. (hereinafter "ASSIGNEE"), a Delaware corporation, with its principal place of business at 5775 Morehouse Drive, San Diego, California 92121, U.S.A, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, we, the said inventors, do hereby acknowledge that we have sold, assigned, transferred, and set over, and by these presents do hereby sell, assign, transfer, and set over, unto the said ASSIGNEE, its successors, legal representatives, and assigns, the entire right, title, and interest throughout the world in, to, and under the said improvements, and the said application and all provisional application(s) to which said Application claims, or is entitled to claim, priority, and all divisions, renewals, and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals, and reissues thereof; and we hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives, and assigns, in accordance with the terms of this instrument.

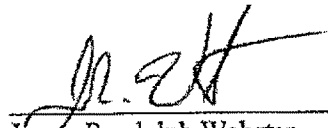
AND WE DO HEREBY sell, assign, transfer, and convey to the said ASSIGNEE, its successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the rights assigned hereby that may have accrued prior to the date of assignment to the said ASSIGNEE, or may accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of the said Letters Patent before or after issuance.

AND WE HEREBY covenant and agree that we will communicate to the said ASSIGNEE, its successors, legal representatives, and assigns, any facts known to me respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, and reissue applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives, and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

Application No.: 12/133,813  
Filing Date: June 5, 2008

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Client Code: QCO.256A/080313  
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2008. IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 13<sup>th</sup> day of June

  
James Randolph Webster

IN TESTIMONY WHEREOF, acknowledged by QUALCOMM MEMS Technologies, Inc. this  
\_\_\_\_ day of \_\_\_\_\_, 20\_\_.

QUALCOMM MEMS Technologies, Inc.

\_\_\_\_\_  
Name:  
Title:

Application No.: 12/133,813  
Filing Date: June 5, 2008

**PATENT**  
Client Code: QCO.256A/080313  
Page 3

IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 20 day of June,  
2008

  
\_\_\_\_\_  
Thanh Nghia Tu

IN TESTIMONY WHEREOF, acknowledged by QUALCOMM MEMS Technologies, Inc. this  
\_\_\_\_ day of \_\_\_\_\_, 20\_\_\_\_.

QUALCOMM MEMS Technologies, Inc.

\_\_\_\_\_  
Name:  
Title:

Application No.: 12/133,813  
Filing Date: June 5, 2008

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Client Code: QCO.256A/080313  
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IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 13 day of June 2008

Xiaoming Yan

IN TESTIMONY WHEREOF, acknowledged by QUALCOMM MEMS Technologies, Inc. this  
\_\_\_\_ day of \_\_\_\_\_, 20\_\_\_\_.

QUALCOMM MEMS Technologies, Inc.

\_\_\_\_\_  
Name:  
Title:

Application No.: 12/133,813  
Filing Date: June 5, 2008

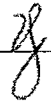
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Client Code: QCO.256A/080313  
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2008 IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 13 day of June,

  
Wonsuk Chung

IN TESTIMONY WHEREOF, acknowledged by QUALCOMM MEMS Technologies, Inc. this  
\_\_\_\_ day of \_\_\_\_\_, 20\_\_.

QUALCOMM MEMS Technologies, Inc.

Name:   
Title:

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